

IN THE SPECIFICATION:

*Please replace the paragraph beginning on page 9, line 1 and ending on page 9, line 6 with the following:*

Anode portion 1033 of capacitor element 1030 is placed on a connecting surface of anode terminal 1037, and cathode layer ~~1034~~ 1036 is placed on a connecting surface of cathode terminal 1038. Connecting portions 1037A of the connecting surface of anode terminal 1037 are folded and joined to anode portion 1033 by resistance welding. Cathode layer ~~1034~~ 1036 is connected to the connecting surface of cathode terminal 1038 with conductive silver paste. Guides 1038A are formed by bending portions of the connecting surface of cathode terminal 1038.

*Please replace the paragraph on page 12, line 24 with the following:*

~~691~~ 619 Cathode Terminal

*Please replace the paragraph beginning on page 20, line 10 and ending on page 20, line 20 with the following:*

Fig. 6A is a plan view of substrate 513 having a hoop shape for providing plural anode terminals 510 and cathode terminals 511. Fig. 6B is a cross sectional view of substrate 513 at line 6B-6B shown in Fig. 6A. Substrate 513 is made of copper alloy, and has feed holes 513A formed therein for intermittent feeding. The anode terminals 510 and cathode terminals 511 are formed consecutively in substrate 513 at predetermined intervals. Plural capacitor element units 5101A are placed on and joined to respective ones of anode terminals 510 and cathode terminals 511, and are covered with resin packages 512, respectively. Then, anode terminals 510 and cathode terminals 511 are removed from substrate 513 to provide plural chip capacitors ~~501~~ 5101.

*Please replace the paragraph beginning on page 21, line 3 and ending on page 21, line 14 with the following:*

Solid electrolytic capacitor ~~504~~ 5101 according to Embodiment 2 allows both anode portion 504 and cathode portion 505 of capacitor element 501 to be drawn out to the outside in a short distance through anode terminal 510 and cathode terminal 511 having flat plate shapes. Further, surface 511G of cathode terminal 511 is arranged as close to surface 510G of anode terminal 510 as possible in order to reduce the distance between anode terminal 510 and cathode terminal 511 to a shortest possible value, thereby providing a small equivalent series resistance (ESR) and a small equivalent series inductance (ESL). The ESL of solid electrolytic capacitor 5101 of Embodiment 2 was 500pH, which was approximately one third of an ESL of 1500pH of conventional solid electrolytic capacitor 1100 shown in Figs. 22 to 24.

*Please replace the paragraph beginning on page 22, line 28 and ending on page 23, line 19 with the following:*

Lower surface 514G of cathode terminal 514 is arranged to be flush with lower surface 510G (a mounting surface when mounted to a mount body, such as a wiring board) of anode terminal 510, and is positioned as close to lower surface 510G of anode terminal 510 as possible. Distance L2 between surface 514G of cathode terminal 514 and surface 510G of anode terminal 510 is not less than 1mm, and preferably is 1mm. The distance being less than 1mm may cause a current leakage across the surfaces. Cathode terminal 514 includes thick portion 514E having surface 514G and thin portion 514A. Thin portion 514A is thinner than thick portion 514E, and extends from thick portion 514E in a direction opposite to anode terminal 510. Surface 514K of thin portion 514A opposite to a surface of the thin portion facing capacitor element 501 is covered with resin package 512 and does not expose, thus not functioning as a mounting surface

arranged to be mounted to the mount body,. Cathode terminal 514 includes mounting portion 514C at an end of thin portion 514A opposite to anode terminal 510. The mounting portion 514C has lower surface 514L functioning as a mounting surface when the capacitor is mounted. Surface 514L is flush with surfaces 510G and ~~511G~~ 514G. Mounting portion 514C extends outward to provide protruding portion 514D of cathode terminal 514 protruding from resin package 512.

*Please replace the paragraph beginning on page 30, line 12 and ending on page 30, line 22 with the following:*

Fig. 12A is a plan view of substrate 613 having a hoop shape for providing plural anode terminals 610 and cathode terminals 611. Fig. 12B is a cross sectional view of substrate 613 at line 12B-12B shown in Fig. 12A. Substrate 613 is made of copper alloy, and has feed holes 613A formed therein for intermittent feeding. Plural anode terminals 610 and cathode terminals 611 are formed consecutively in substrate 613 at predetermined intervals. Plural capacitor element units 6101A are placed on and joined to respective ones of plural anode terminals 610 and cathode terminals 611, and are covered with resin packages 612, respectively. Anode terminals 610 and cathode terminals 611 are then removed from substrate 613 to provide plural chip capacitors ~~601~~ 6101.

*Please replace the paragraph beginning on page 30, line 12 and ending on page 30, line 22 with the following:*

Solid electrolytic capacitor ~~601~~ 6101 according to Embodiment 6 allows both anode portion 604 and cathode portion 605 of capacitor element 601 to be drawn to the outside in a short distance through anode terminal 610 and cathode terminal 611 having flat plate shapes. Further, surface 611G of cathode terminal 611 is arranged as close to surface 610G of anode terminal 610 as possible in order to reduce the distance between anode terminal 610 and cathode terminal 611 to a shortest possible value, thereby providing the capacitor with a small equivalent series resistance (ESR) and a small equivalent series inductance (ESL). The ESL of solid electrolytic capacitor 6101 of Embodiment 6 was ~~800pH~~ 500pH, which is about ~~a-half~~ one third of an ESL of 1500pH of conventional solid electrolytic capacitor 1100 shown in Figs. 22 to 24.